

TWENTY THIRD ANNUAL



TestConX™

May 1 - 4, 2022

DoubleTree by Hilton  
Mesa, Arizona

**Archive**

# The Next Generation of True Kelvin Spring Probes

**Bert Brost**

**Technoprobe**

**Ming-Ting Wu**

**Microfabrica**



Mesa, Arizona • May 1-4, 2022



## Contents

- Need for Low Resistance Measurements
- Four Wire Resistance Measure
- Improved Measurement Accuracy
- Circuit Traces, Test Cables, Wires, and Clips are not a Big Deal Anymore
- Device-Under-Test Traditional Two-Wire Interconnect
- Device-Under-Test Two-Wire Interconnect
- Four-Wire Interconnect at the Test Contactor
- Four-Wire Interconnect at the Device-Under-Test
- The Next Generation of True Kelvin Spring Probes
- WLCSP True Kelvin Requirements
- The Next Generation of True Kelvin Spring Probes
- Summary
- References



The Next Generation of True Kelvin Spring Probes

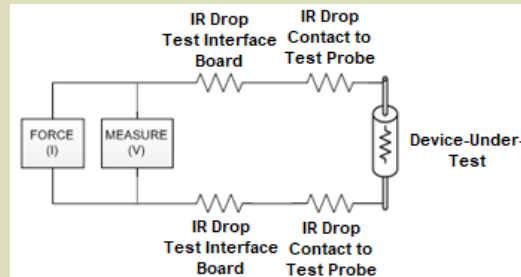
2 2022



## Need for Low Resistance Measurements

The Goal:

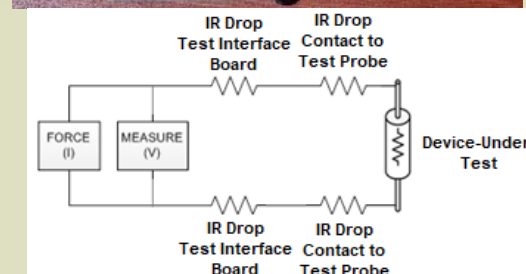
- Reduce errors caused by test interconnect resistance



- Four wire contacting is the most accurate method when measuring resistance below 1.0  $\Omega$ .

## Four Wire Resistance Measure

- If you try to use your multimeter's resistance function, you will get a useless reading:
  - As shown, we have no idea what the resistance of the wire is. We do know that the resistance of the wire is a lot less than  $0.4\ \Omega$ ,  $1.0\ \Omega$ ,  $0.3\ \Omega$ ,  $0.4\ \Omega$
  - Recommended is the use of setups that minimize errors induced by the test interconnect resistance, load board trace resistance, and the resistance of the probe.
- Four Wire Kelvin is error reduction solution



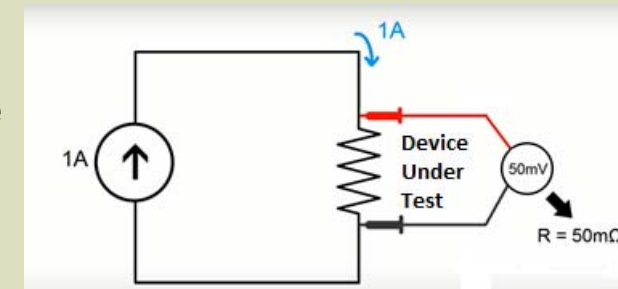
The Next Generation of True Kelvin Spring Probes

4

2022

## Improved Measurement Accuracy

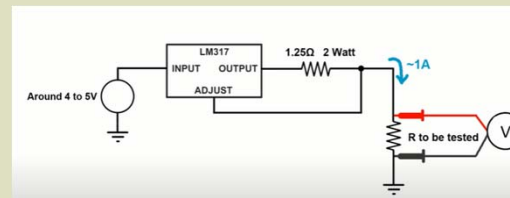
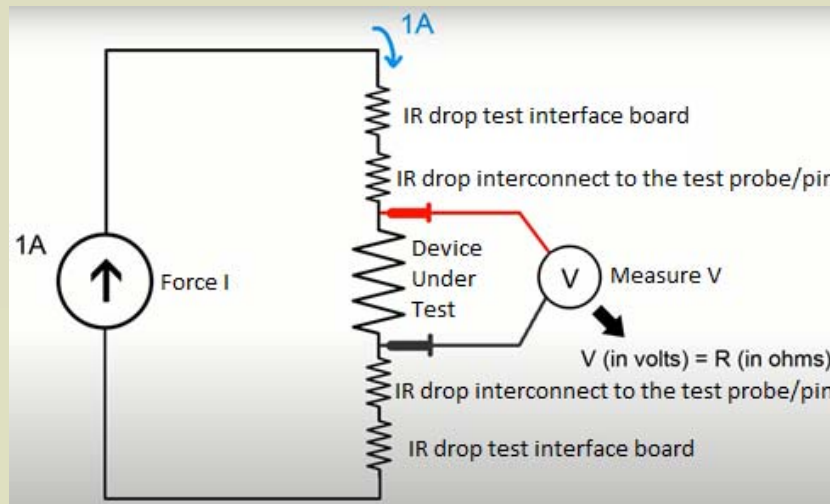
- Let's start with a constant current source of one ampere.
  - Since it is a constant current source, the amount of current flowing through the circuit will always be one ampere.
  - The measuring instrument has a high input impedance.
- For example, we measure 50 millivolts across R.
  - That means that the resistance of the wire is 0.050 Ω



$$R = \frac{E}{I}$$

## Circuit Traces, Test Cables, Wires, and Clips are not a Big Deal Anymore

- The input impedance of the Multimeter is so high, almost no current flows into the multimeter so the meter does not affect the circuit.



- 0-30 Volts, 0-3 Amps
- Constant Voltage, Constant Current
- Single Digital Meter with Switchable Volts or Amps Display
- Coarse and Fine Controls for Voltage and Current
- Light and Compact Design
- 0.01% Regulation
- Low Ripple and Noise
- Or you can build your own



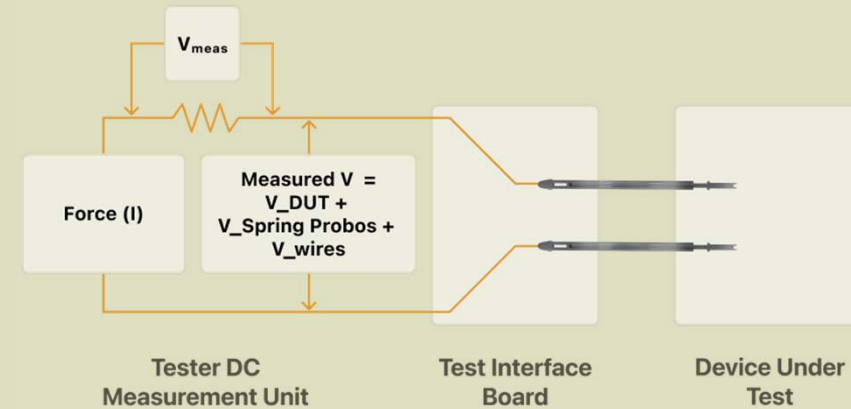
The Next Generation of True Kelvin Spring Probes

6

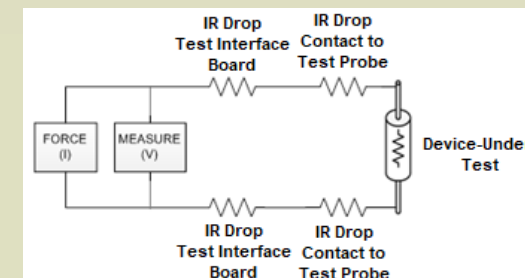
2022

## Device-Under-Test Traditional Two-Wire Interconnect

- Shown here is a basic block diagram of an automatic test equipment (ATE) measurement circuit with some of the interconnects to the device-under-test.
  - The current flowing through the device-under-test is in series with the current flowing through test system interconnects to the test interface board, the test interface board, and the contact probe. This is because there is only one series path for current to flow.



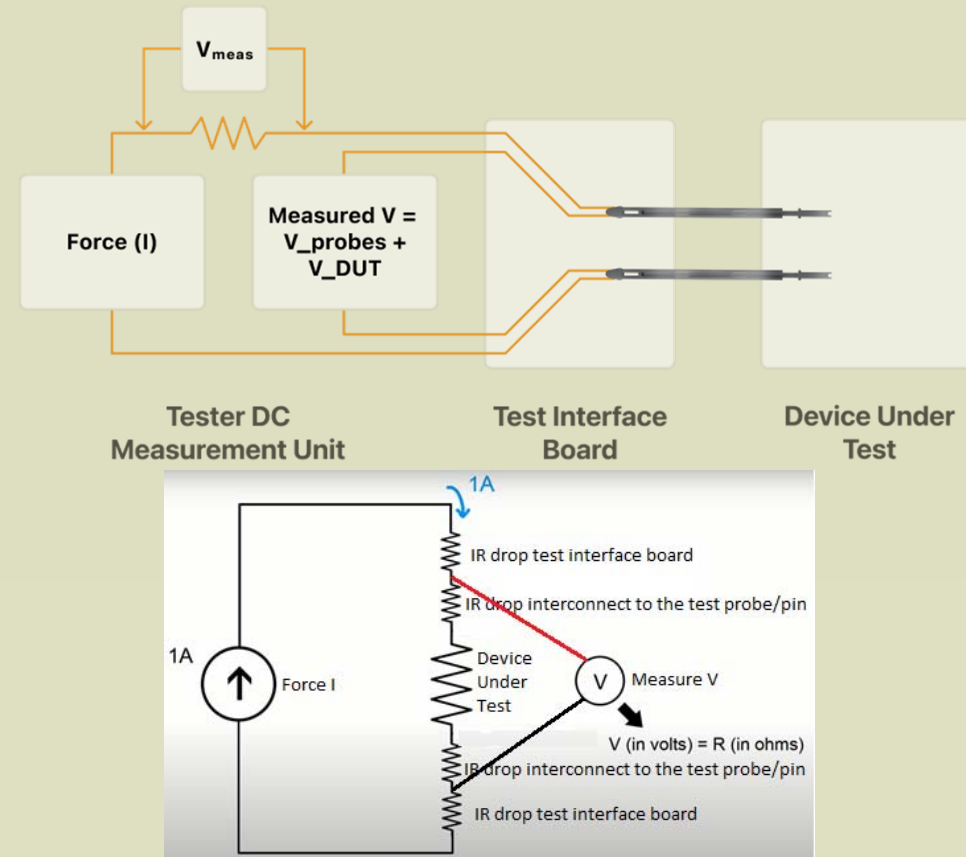
### Traditional Two-Wire Interconnect Equivalent Circuit





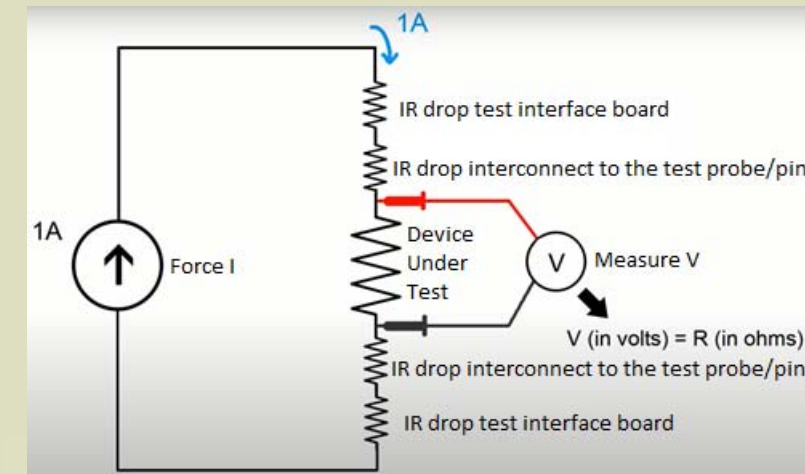
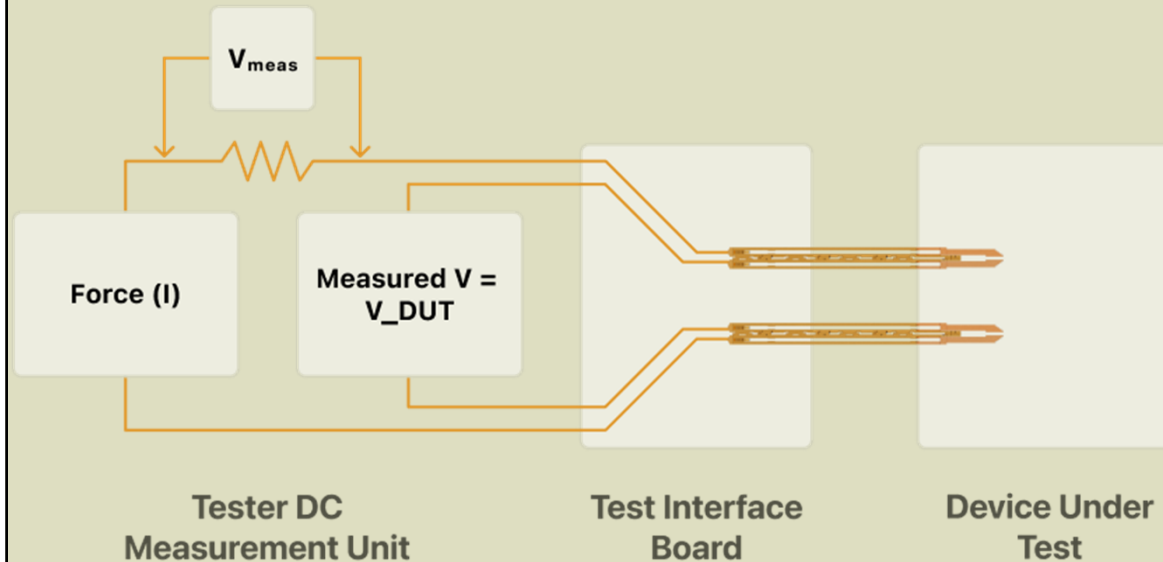
## Four-Wire Interconnect at the Test Contactor

- Four wire connection at the contactor involves shorting the force and sense lines at spring probe the test interface board interconnect pad.
  - This method is used when an accurate measurement is desired, but Kelvin contacting at the device-under-test is not practically feasible.
- The four-wire sense measurement at the test interface board pad.
- This method of sensing provides the tester's measurement unit with the voltage level at the point where the contactor and the test interface board connect.



## Four-Wire Interconnect at the Device-Under-Test

- Four wire connection at the Device-Under-Test



As shown, the sense path is a direct connect from the precision measurement unit all the way to the device-under-test. This is the best way to eliminate possible measurement errors caused by a voltage drop anywhere in the sense circuit.

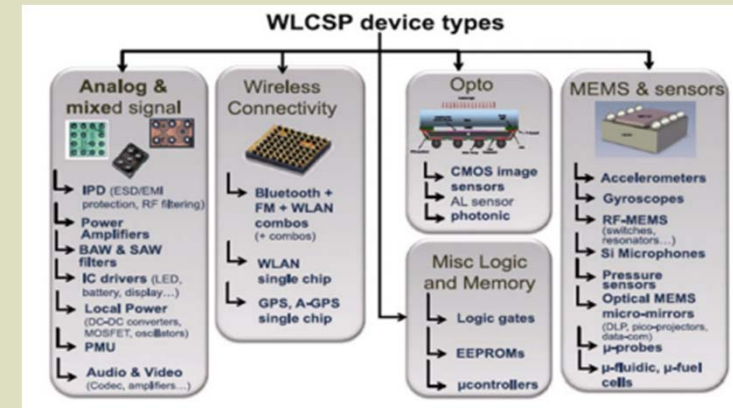
## The Next Generation of True Kelvin Spring Probes

- Needs driving a new generation of advanced package four-wire Kelvin contacting technology:

- Increasing I/O density
  - Pitch shrink
  - Demand for full array Kelvin contacting at and below 400-micron pitch
- Higher system integration
- Smaller devices

I/O counts of less than 50 is considered by most to be mature.

There is plenty of activity underway in the industry to extend board level reliability of WLCSP to array size in more than 100 I/O counts with acceptable reliability.



Yannou, J-M.: Market dynamics impact WLCSP adoption, 3D Packages, No. 22, Feb (2012)

## WLCSP True Kelvin Requirements

- True Four Wire Kelvin dual probe criteria.
  - Force and sense probe are electrically insulated.
  - Force and sense probes are mechanically isolated.
  - Probe tips must hit smaller targets.
  - Ball and bump diameters that are  $\geq 200$  microns.
  - Multiple and single site contacting.



- Force and sense probe are electrically insulated.
- Force and sense probes are mechanically isolated.
- 150 micron diameter ball



The Next Generation of True Kelvin Spring Probes

11

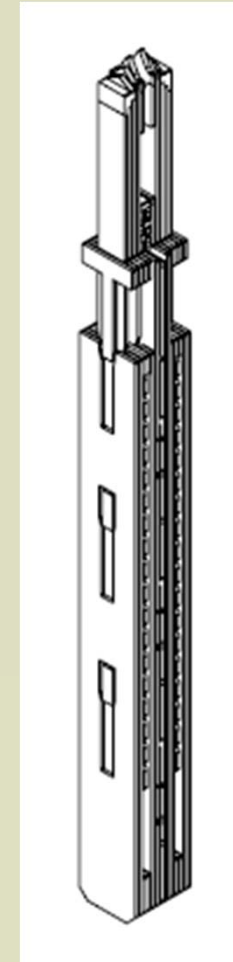
2022



# TestConX 2022

## The Next Generation of True Kelvin Spring Probes

- Modular single probe dual probe construction
- Reduced forces = reduced contactor and probe head bowing
- One hole per dual Kelvin probes in the contactor body
  - Ease of field maintenance
  - Higher I/O density contacting



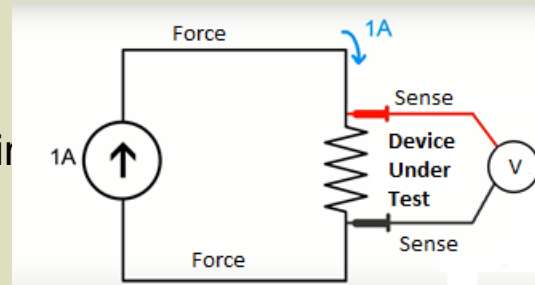
The Next Generation of True Kelvin Spring Probes

12

2022

## Summary

- The Goal: Reduce errors caused by test interconnect resistance
- Precision reliable connections all the way to the device under test.
- In low resistance measurements, the recommended method
  - Force through two wires
  - Measure (sense) through the other two wires
    - That is: four wire Kelvin
- Recommendation:
- Use four wire Kelvin interconnects when testing power controllers, voltage regulators, and mixed signal devices where precision is required.



## References

1. **Shichun Qu, Yong Liu: Wafer-Level Chip-Scale Packaging, Analog and Power Semiconductor Applications.**  
Springer New York Heidelberg Dordrecht London (2015)
2. **4-Wire Kelvin Testing**  
Cirris  
<https://www.cirris.com/learning-center/general-testing/special-topics/40-4-wire-kelvin-testing>
3. **Accurate Low-Resistance Measurements Start with Identifying Sources of Error**  
Dale Cigoy, Senior Applications Engineer, Keithley Instruments, Inc.  
<https://www.tek.com/en/documents/whitepaper/accurate-low-resistance-measurements-start-identifying-sources-error>
4. **What is Kelvin Test?**  
Rick Meraw and Todd Kolmodin, Gardien Services USA Manfred Ludwig, Gardien Services China  
Holger Kern, Gardien Services Germany  
[https://www.circuitinsight.com/pdf/what\\_is\\_kelvin\\_test\\_ipc.pdf](https://www.circuitinsight.com/pdf/what_is_kelvin_test_ipc.pdf)
5. **Kelvin (4-wire) Resistance Measurement**  
All About Circuits, Chapter 8 – DC Metering Circuits  
<https://www.allaboutcircuits.com/textbook/direct-current/chpt-8/kelvin-resistance-measurement/>

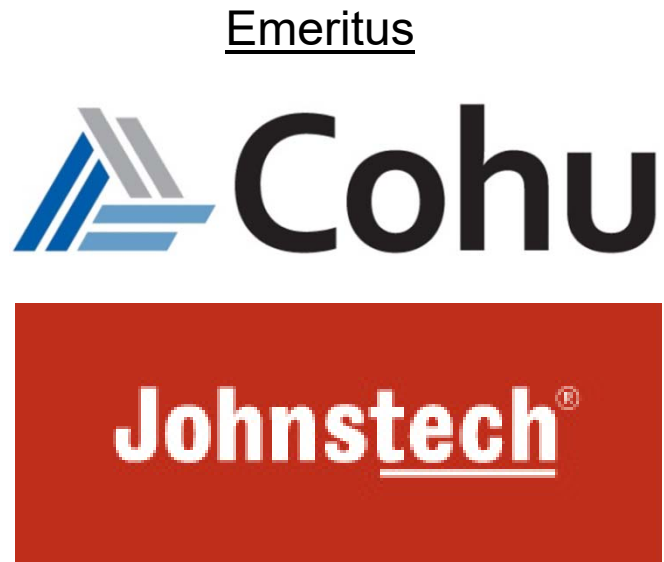


The Next Generation of True Kelvin Spring Probes

14 2022

# With Thanks to Our Sponsors!

Premier  
**HiCon**





# With Thanks to Our Sponsors!

## Distinguished



## Industry Partners



# With Thanks to Our Sponsors!

Lanyards



Tutorial



Keynote

smiths  
interconnect

Keycards



Totebag



Publication Sponsor



# COPYRIGHT NOTICE

The presentation(s) / poster(s) in this publication comprise the Proceedings of the TestConX 2022 workshop. The content reflects the opinion of the authors and their respective companies. They are reproduced here as they were presented at the TestConX 2022 workshop. This version of the presentation or poster may differ from the version that was distributed at or prior to the TestConX 2022 workshop.

The inclusion of the presentations/posters in this publication does not constitute an endorsement by TestConX or the workshop's sponsors. There is NO copyright protection claimed on the presentation/poster content by TestConX. However, each presentation / poster is the work of the authors and their respective companies: as such, it is strongly encouraged that any use reflect proper acknowledgement to the appropriate source. Any questions regarding the use of any materials presented should be directed to the author(s) or their companies.

“TestConX”, the TestConX logo, and the TestConX China logo are trademarks of TestConX. All rights reserved.

**[www.testconx.org](http://www.testconx.org)**